

MBRF3060CT

Rev.F Mar.-2016

/ Descriptions

KF $\text{S})' =$

Schottky Barrier Diode in a TO-220F Plastic Package.

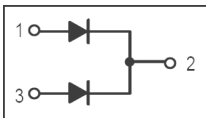
/ Features

Low power loss,high efficiency.

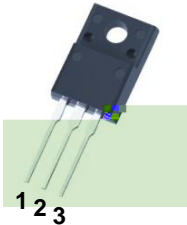
/ Applications

For use in low voltage,high frequency inverters, free wheeling, and polarity protection applications.

/ Equivalent Circuit



/ Pinning



PIN1 Anode PIN 2 Cathode PIN 3 Anode

/ h_{FE} Classifications & Marking

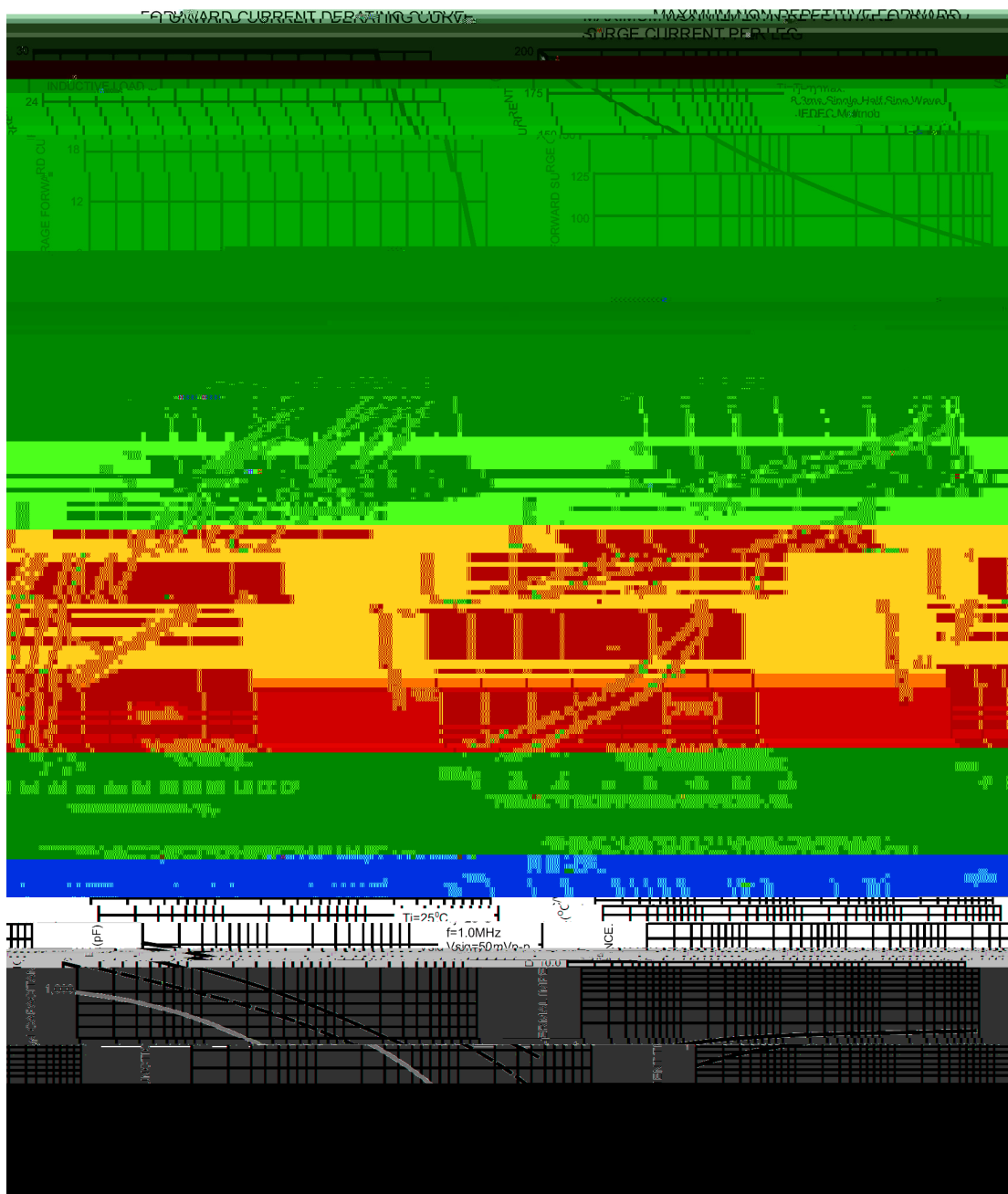
See Marking Instructions

MBRF3060CT

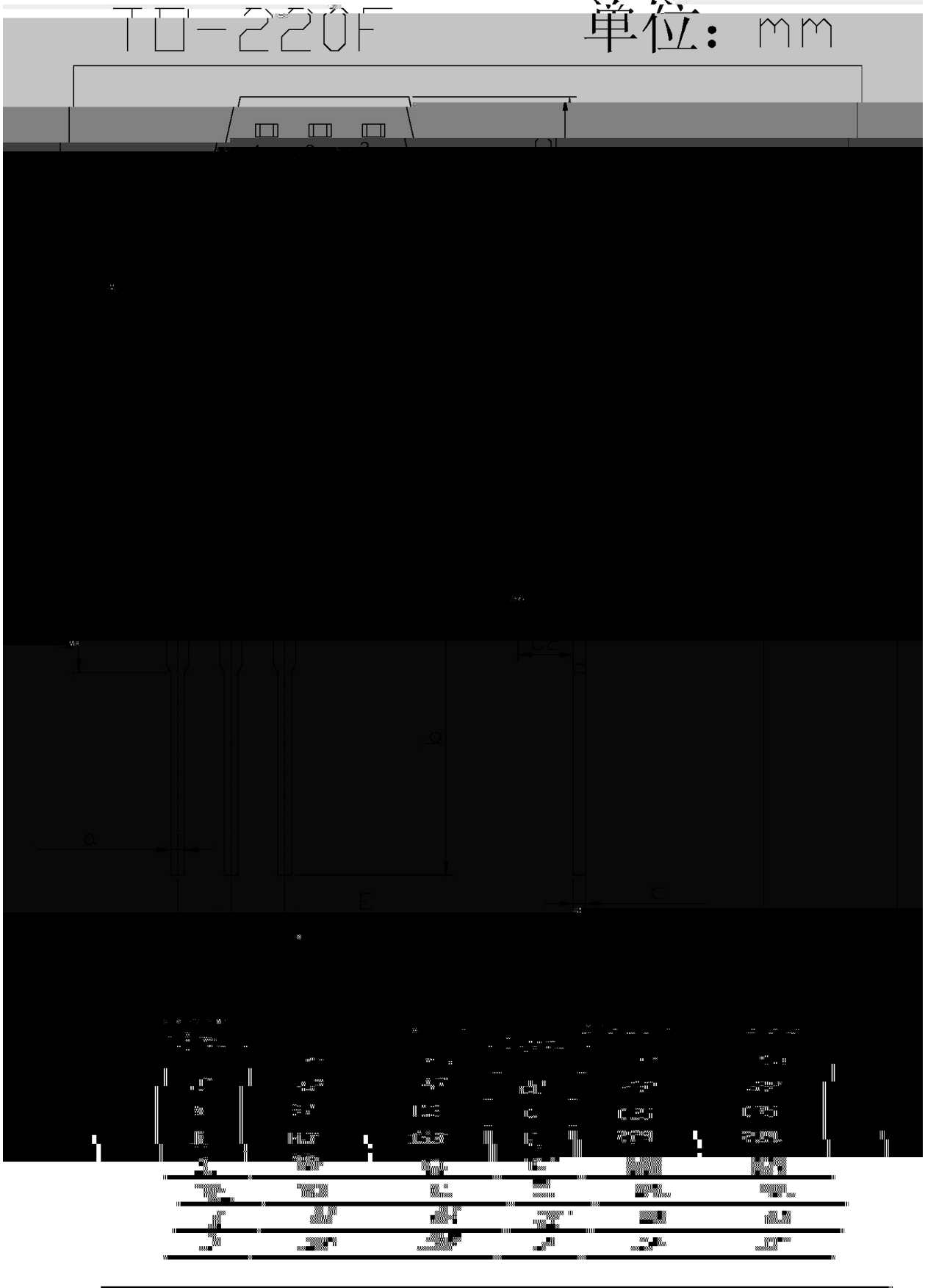
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Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	60	V
RMS forward current	V_{RMS}	42	V
DC Blocking Voltage	V_{DC}	60	V
Average Forward Current	$I_{F(AV)}$	15	A
Average Forward Current(total device)	$I_{F(AV)}$ total device	30	A
Non Repetitive Peak Surge Current	I_{FSM}	200	A
Instantaneous Reverse Current	I_{FRM}	30	A
Peak Repetitive Reverse Current	I_{RRM}	0.5	A
Thermal Resistance Junction to Case	R_{Jc}	1.0	/W

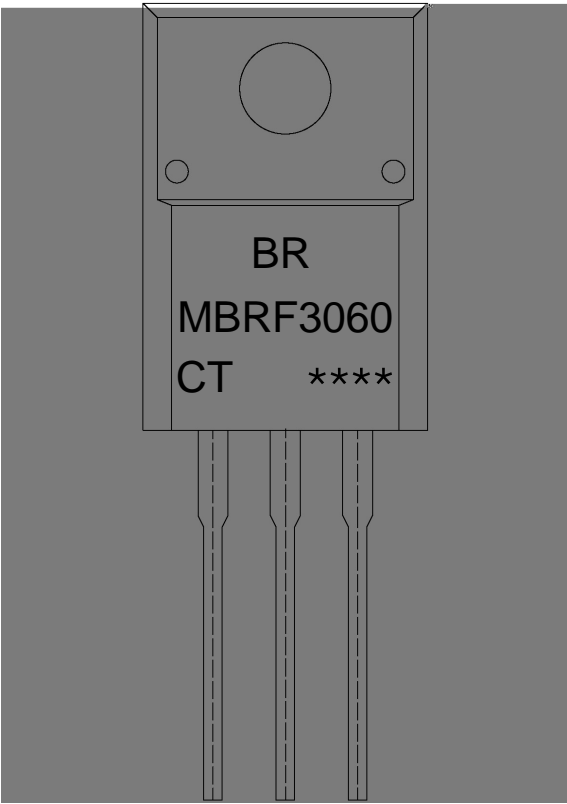
/ Electrical Characteristic Curve



/ Package Dimensions



/ Marking Instructions



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: K1

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Note:

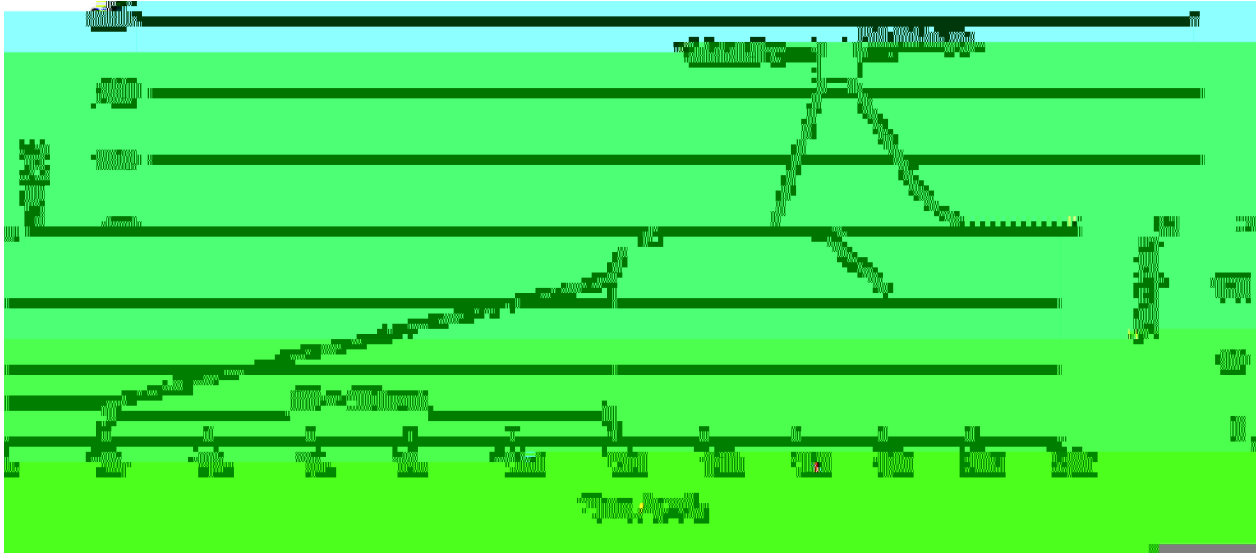
BR: Company Code

MBRF3060: Product Type.

CT: Internal Structure

****: Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- | | | | |
|---|--------|------------|---|
| 1 | 25 150 | 60 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 255..5 | 5..0.5sec; | 2.Peak Temp.:255..5 , Duration:5..0.5sec. |
| 3 | 2 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

270..5 10..1 sec. Temp.:270±5 Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type	Units					Dimension (unit mm ³)		
	Units/Bag /	Bags/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Bag	Inner Box	Outer Box
TO-220/F	200	10	2,000	5	10,000	135×190	237×172×102	560×245×195

/ TUBE

Package Type	Units					Dimension (unit mm ³)
	Units/Tube /	Tubes/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	